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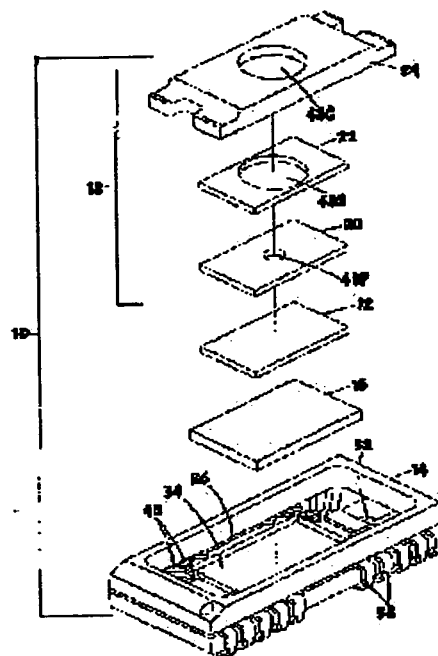
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## (54) METHOD AND APPARATUS FOR PACKAGING AND TESTING SEMICONDUCTOR DIE

(57)Abstract:

**PROBLEM TO BE SOLVED:** To make it possible to use a standard burn-in board and automated package handling apparatus by forming a temporary package for a semiconductor die having a standard profile and external lead shape, and testing the die by using the package and standard testing unit.

**SOLUTION:** A temporary package 10 holds a semiconductor die 12 and forms a temporary electric connection to a die 12 for testing and burning-in. After the test was finished, the die 12 is removed from the package 10, and used as the test acceptance die. That is, the package 10 has a package base 14, interconnect 16, and a pressurizing mechanism 18. The interconnect 16 electrically connect the base 14 with the die 12. The package 10 is assembled as a small outline package having a J bend lead 38, and can be burned-in by using a standard burn-in unit for normal small outline J bend package.



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